



Final Product Change Notification

202204015F01 : MCF5282 and MCF5216 Fab Site Expansion from TSMC3 to NXP-CHD

Note: This notice is NXP Company Proprietary.

Issue Date: Sep 01, 2022 **Effective date:** Nov 30, 2022

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Management summary

Wafer Fabrication site expansion for the MCF5282 and MCF5216 from Fab 3(TSMC3),Taiwan Wafer Fabrication site to the NXP CHD Fab Chandler, Arizona Wafer Fabrication site.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input checked="" type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

PCN Overview

Description

NXP Semiconductors announces the Wafer Fabrication site expansion for the MCF5282 and MCF5216 associated with this notification, from the current Taiwan Semiconductor Manufacturing Company Fab 3(TSMC3),Taiwan Wafer Fabrication site to the NXP CHD Fab Chandler, Arizona Wafer Fabrication site.

Wafer Fabrication site expansion was successfully qualified adhering to NXP specifications.

Please see the attached file(s) for additional details.

Reason

Qualification of NXP CHD Fab Chandler, Arizona is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Top Side Marking

The mask marking for CHD will reflect 0N04K, while the mask marking for TSMC3 will remain 2L95M

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Nov 27, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Fab Expansion. No Depletion of Inventory required.

Additional information

Self qualification: view online

Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Oct 01, 2022.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
MCF5214CVF66	935309487557	MCF5214CVF66	MCF5214 V2CORE 256KFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1
MCF5214CVM66	935313607557	MCF5214CVM66	MCF5214 V2CORE 256KFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1
MCF5216CVM66	935312409557	MCF5216CVM66	MCF5216 V2CORE 512KFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1
MCF5216CVF66	935313608557	MCF5216CVF66	MCF5216 V2CORE 512KFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1
MCF5281CVM80	935309494557	MCF5281CVM80	MCF5281 V2CORE 256KFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1
MCF5282CVM66	935311806557	MCF5282CVM66	MCF5282 V2CORE 512KFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1
MCF5280CVF66	935319122557	MCF5280CVF66	MCF5280 V2CORE NOFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1
MCF5280CVM66	935321089557	MCF5280CVM66	MCF5280 V2CORE NOFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1
MCF5282CVM80	935321091557	MCF5282CVM80	MCF5282 V2CORE 512KFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1
MCF5282CVF80	935321176557	MCF5282CVF80	MCF5282 V2CORE 512KFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1
MCF5280CVM80	935322685557	MCF5280CVM80	MCF5280 V2CORE NOFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1
MCF5282CVF66	935322686557	MCF5282CVF66	MCF5282 V2CORE 512KFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1
MCF5281CVM66	935324042557	MCF5281CVM66	MCF5281 V2CORE 256KFLASH	(L)BGA256M	SOT740-4	RFS	No	BLM1